

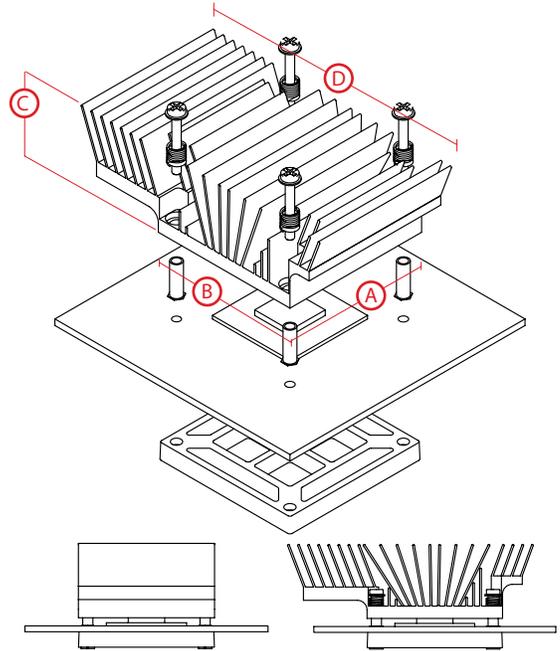


High Performance LGA Cooling Solutions

ATS PART # ATS-57001-C1-R0

Features & Benefits

- » Provides high capacity cooling for high power LGAs
- » Unique attachment minimizes mechanical stress on the device
- » Includes spring-loaded, push pin mounts for direct attachment to the PCB



**Image above is for illustration purposes only.*

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	1.01	0.6	
300	1.5	0.81		
400	2.0	0.7		
500	2.5	0.62		
600	3.0	0.57		
700	3.5	0.52		
800	4.0	0.48		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
56 mm	56 mm	31 mm	N/A mm	NO TIM	BLACK-ANODIZED

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 3) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Contact ATS to learn about custom options available.



ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).